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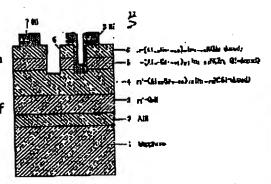
KOIKE MASAYOSHI

(54) METHOD FOR MANUFACTURE OF GROUP III NITRIDE SEMICONDUCTOR

(57)Abstract:

PURPOSE: To make hydrogen leave from a film and to prevent nitrogen from leaving the film by substituting atmospheric gas for an inactive gas other than H2 gas and NH3 gas until a room temperature is reached after the vapor growth of group III nitride semiconductor.

CONSTITUTION: AIN buffer layer 2 is formed on a sapphire substrate 1 and then a high-carrier concentration n+ layer 3 consisting of GaN, a high-carrier concentration n+ layer 4 consisting of (Alx2Ga1-x2)y2In1-y2N, a light-emitting layer 6 consisting of (Alx1Ga1-x1)y1N, and p-layer 6 consisting of (Alx2Ga1-x2)y2 In1-y2N are formed on the buffer layer 2. Then, the supply of organic metal gas is stopped and the inside of a reaction room is exhausted in vacuum and then the inside is naturally cooled to a room temperature by introducing N2 gas or inactive gas, thus enabling the p-layer 6 to be p-type semiconductor with a



Hall concentration of 6 × 1017/cm2 and a resistivity of 20cm. As a result, by improving the crystallizability of a semiconductor thin film using AlGaInN, the light emitting intensity of a light-emitting element using the semiconductor can be improved.

LEGAL STATUS

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